



## **PROCESS CHANGE NOTICE PCN0119**

### **FineLine BGA™ Package Molding Compound Change**

#### **Change Description:**

ASAT Hong Kong will change the FineLine BGA™ package molding compound from Shin Etsu to Nitto HC-100. This change will not affect the package thickness specification, overall package dimensions, or the moisture rating for these packages.

#### **Reason For Change:**

The FineLine BGA™ package molding compound is changing from Shin Etsu to Nitto HC-100 to improve package coplanarity during high-temperature reflow.

#### **Products Affected:**

All MAX, FLEX, APEX, and ACEX family FineLine BGA™ packages assembled at ASAT Hong Kong.

Initial products affected will include:

EPF10K100E 484-Ball FineLine BGA™

EPF10K130E 484-Ball FineLine BGA™

EP20K200E 484-Ball FineLine BGA™

EPF10K200S 672-Ball FineLine BGA™

EPF10K200E 672-Ball FineLine BGA™

EP20K200E 672-Ball FineLine BGA™

EP20K300E 672-Ball FineLine BGA™

#### **Product Traceability and Transition Dates:**

Product assembled with Nitto-HC100 molding compound will begin shipping on or after February 15, 2002 and can be distinguished by the topside marked date code of 0213 or later.

#### **Contact:**

Qualification reports are available upon request. For additional information regarding the changes described in this document, please contact the Altera Customer Quality Engineering Department at (408) 544-6933.